

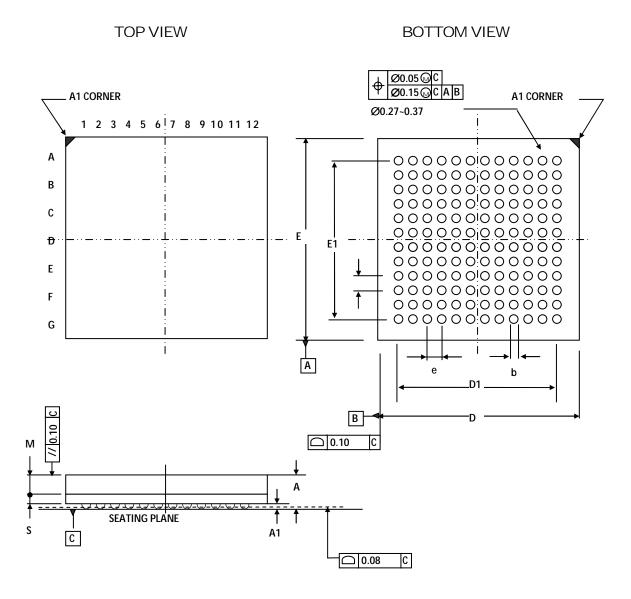
Controlled Document

Package Outline Drawing

V144.7X7A

144 Lead Thin, Fine Pitch Plastic ball Grid Array Package (TFBGA)

Rev 0, 1/11



Title: Specification Type: POD Specification Number: V144.7X7A

 $144\ Lead\ Thin, Fine\ Pitch\ Plastic\ ball\ Grid\ Array\ Package\ (TFBGA)$

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	Millimeter		
Symbol	Min.	Nom.	Max.
А			1.20
A1	0.16		0.26
М	0.53 Ref.		
S	0.26 Ref.		
b	0.27	0.30	0.37
e	0.50 Basic		
D	6.90	7.00	7.10
D1		5.50	
E	6.90	7.00	7.10
E1		5.50	

Note:

- 1. Primary datum C and seating plane are defined by the spherical crowns of the solder balls.
- 2. Dimension b is measured at the maximum solder ball diameter, parallel to primary datum C.
- 3. Controlling dimension: Millimeter.

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